

L Number	Hits	Search Text	DB	Time stamp
1	2	("2002170919").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/14 11:47
-	4	257/737-738.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:37
-	1	257/779.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:38
-	0	257/685-686.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:39
-	577	257/685-686.ccls. and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:43
-	0	257/685-686.ccls. and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:44
-	128	257/685-686.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:54
-	157	438/613-617.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 16:18
-	90	438/612.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:14
-	419	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:16
-	136	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4) and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:22
-	1	(atomic adj beam) with (inactive adj gas adj excited) near3 plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:23
-	1	(atomic adj beam) with (inactive adj gas adj excited) with plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:24

-	1	(atomic adj beam) and (inactive adj gas adj excited) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:25
-	1	irradiating adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
-	1	irradiat\$4 adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
-	0	activating and sputtering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:27
-	9	activat\$4 and sputtering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:29
-	0	activat\$4 with sputtering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:29
-	0	sputterr\$4 and (reduction adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:30
-	0	sputterr\$4 and (reduct\$4 adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:40
-	2	("2002110726").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:56
-	133	multi-layer and solder and intermetallic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:04
-	1603	solder and intermetallic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:04
-	581	solder and intermetallic and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:05
-	310	solder and intermetallic and (bump ball) and press\$4 and (heat\$4 reflow\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:18
-	6	((("6344696")) or ("5633204")) or ("5508561")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:27

-	36	((("5633204") or ("5508561") or ("6259161") or ("6288851") or ("6278190") or ("6344682") or ("6184061") or ("5986336") or ("5959353") or ("6270202") or ("5900582") or ("5969463") or ("5910699") or ("5925973") or ("5724726") or ("5763829") or ("5281818") or ("5291484") or ("4831636")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:35
-	429	(reaction adj layer) and laminat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:03
-	66	(reaction adj layer) and laminat\$4 and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:03
-	17	438/615.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:10
-	580	438/613-617.ccls. and press\$4 and heat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:19
-	488	438/613-617.ccls. and press\$4 and heat\$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:23
-	0	((masamoto adj tago) (Yoshihiro adj tomita)) and press\$4 and heat\$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:02
-	5	tago-masamoto.in. and heat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:11
-	2	tago-masamoto.in. and Tomita-yoshihiro.in. and heat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:12
-	27	Tomita-yoshihiro.in. and heat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 15:18
-	24	((("5229647") or ("5418687") or ("5440241") or ("5506383") or ("5682062") or ("5685885") or ("5742100") or ("5767575") or ("5892288") or ("5973396") or ("5990546") or ("6004867")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 15:56
-	3	("3171643").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 11:47

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-	0	257/685-686.ccls. and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:44
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-	136	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4) and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:22
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-	1	(atomic adj beam) and (inactive adj gas adj excited) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:25

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-	1	irradiat\$4 adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
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-	0	sputterr\$4 and (reduction adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:30
-	0	sputterr\$4 and (reduct\$4 adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:40
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-	0	((masamoto adj tago) (Yoshihiro adj tomita)) and press\$4 and heat\$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:02
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